	Type	Hits	Search Text	DBs
1	BRS	1	US-6251488-$.DID. OR US-US6259962-$.DID. OR US-US6268584-$.DID. OR US-US639251-$.DID.	USPAT
2	BRS	4	US-6251488-$.DID. OR US-6259962-$.DID. OR US-6268584-$.DID. OR US-6391251-$.DID.	USPAT
3	BRS	0	20020171777-$.DID. OR 20030151167-$.DID.	USPAT; US-PGPUB
4	BRS	2	20020171777.pn. OR 20030151167.pn.	USPAT; US-PGPUB
5	BRS	2	20020171177.pn. OR 20030151167.pn.	USPAT; US-PGPUB
6	BRS	506959	throughhole or through adj hole or via adj hole or viahole	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
7	BRS	3018261	photopolymer or polymer or resin or epoxy	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
8	BRS	33758	laser near4 (cur$4 or harden$4 or consolidat$4 or ossif$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
9	BRS	103	(throughhole or through adj hole or via adj hole or viahole) same (laser near4 (cur$4 or harden$4 or consolidat$4 or ossif$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
10	BRS	103	((throughhole or through adj hole or via adj hole or viahole) same (laser near4 (cur$4 or harden$4 or consolidat$4 or ossif$4))) and (@ad < "20030916")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
11	BRS	25	(throughhole or through adj hole or via adj hole or viahole) same (laser near4 (cur$4 or harden$4 or consolidat$4 or ossif$4)) same (photopolymer or polymer or resin or epoxy)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
12	BRS	13	(throughhole or through adj hole or via adj hole or viahole) same (laser near4 (cur$4 or harden$4 or consolidat$4 or ossif$4)) near8 (photopolymer or polymer or resin or epoxy)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

Type	Hits	Search Text	DBs
13 BRS	0	((throughhole or through adj hole or via adj hole or viahole) same (laser near4 (cur$4 or harden$4 or consolidat$4 or ossif$4)) near8 (photopolymer or polymer or resin or epoxy)) not ((throughhole or through adj hole or via adj hole or viahole) same (laser near4 (cur$4 or harden$4 or consolidat$4 or ossif$4)) same (photopolymer or polymer or resin or epoxy))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
14 BRS	12	((throughhole or through adj hole or via adj hole or viahole) same (laser near4 (cur$4 or harden$4 or consolidat$4 or ossif$4)) same (photopolymer or polymer or resin or epoxy)) not ((throughhole or through adj hole or via adj hole or viahole) same (laser near4 (cur$4 or harden$4 or consolidat$4 or ossif$4)) near8 (photopolymer or polymer or resin or epoxy))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
15 BRS	3022763	substrate or wafer or die or chip or ic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
16 BRS	507324	throughhole or through adj hole or via adj hole or viahole	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
17 BRS	0	trepn$4 same (throughhole or through adj hole or via adj hole or viahole) same (substrate or wafer or die or chip or ic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
18 BRS	0	trepn$4 and (throughhole or through adj hole or via adj hole or viahole) and (substrate or wafer or die or chip or ic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

Type	Hits	Search Text	DBs
19	BRS	0	trepn$4 and (throughhole or through adj hole or via adj hole or viahole)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
20	BRS	1617	trepan$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
21	BRS	2	trepn$4 and (substrate or wafer or die or chip or ic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
22	BRS	14	trepan$4 same (throughhole or through adj hole or via adj hole or viahole) same (substrate or wafer or die or chip or ic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
23	BRS	3140914	photopolymer or polymer or resin or epoxy or thermoset$4 or thermoplastic$4 or thermo adj (set$6 or plastic$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
24	BRS	4719	(throughhole or through adj hole or via adj hole or viahole) near2 (photopolymer or polymer or resin or epoxy or thermoset$4 or thermoplastic$4 or thermo adj (set$6 or plastic$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
25	BRS	3938724	cur$4 or harden$4 or consolidat$4 or ossif$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
26	BRS	210824	(photopolymer or polymer or resin or epoxy or thermoset$4 or thermoplastic$4 or thermo adj (set$6 or plastic$4)) near2 (cur$4 or harden$4 or consolidat$4 or ossif$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

Type	Hits	Search Text	DBs
27	BRS	965	((throughhole or through adj hole or via adj hole or viahole) near2 (photopolymer or polymer or resin or epoxy or thermoset$4 or thermoplastic$4 or thermo adj (set$6 or plastic$4))) and ((photopolymer or polymer or resin or epoxy or thermoset$4 or thermoplastic$4 or thermo adj (set$6 or plastic$4)) near2 (cur$4 or harden$4 or consolidat$4 or ossif$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
28	BRS	2421605	edge or border or perimeter or circumferance	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
29	BRS	46363315	throughhole or through adj hole or via adj hole or viahole or open$4 or recess or aperature	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
30	BRS	86	(throughhole or through adj hole or via adj hole or viahole or open$4 or recess or aperature) same ((photopolymer or polymer or resin or epoxy or thermoset$4 or thermoplastic$4 or thermo adj (set$6 or plastic$4)) near2 (cur$4 or harden$4 or consolidat$4 or ossif$4)) near4 (edge or border or perimeter or circumferance)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
31	BRS	27	((throughhole or through adj hole or via adj hole or viahole or open$4 or recess or aperature) same ((photopolymer or polymer or resin or epoxy or thermoset$4 or thermoplastic$4 or thermo adj (set$6 or plastic$4)) near2 (cur$4 or harden$4 or consolidat$4 or ossif$4)) near4 (edge or border or perimeter or circumferance)) and (substrate or wafer or die or chip or ic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

Type	Hits	Search Text	DBs
32	BRS	3022763	substrate or wafer or die or chip or ic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
33	BRS	27	((throughhole or through adj hole or via adj hole or viahole or open$4 or recess or aperature) same ((photopolymer or polymer or resin or epoxy or thermoset$4 or thermoplastic$4 or thermo adj set$6 or plastic$4)) near2 (cur$4 or harden$4 or consolidat$4 or ossif$4)) near4 (edge or border or perimeter or circumferance)) and (substrate or wafer or die or chip or ic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
34	BRS	178	(throughhole or through adj hole or via adj hole or viahole or open$4 or recess or aperature) same ((photopolymer or polymer or resin or epoxy or thermoset$4 or thermoplastic$4 or thermo adj set$6 or plastic$4)) near2 (cur$4 or harden$4 or consolidat$4 or ossif$4)) same (drill$4 or etch$4 or laser$4) near4 (throughhole or through adj hole or via adj hole or viahole)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
35	BRS	6715023	coat$4 or lin$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
36	BRS	505	(throughhole or through adj hole or via adj hole or viahole) near4 (coat$4 or lin$4) near4 (photopolymer or polymer or resin or epoxy or thermoset$4 or thermoplastic$4 or thermo adj set$6 or plastic$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

Type	Hits	Search Text	DBs
37 BRS	369	(throughhole or through adj hole or via adj hole or viahole) near4 ((photopolymer or polymer or resin or epoxy or thermoset$4 or thermoplastic$4 or thermo adj (set$6 or plastic$4)) near2 (cur$4 or harden$4 or consolidat$4 or ossif$4)) near4 (photopolymer or polymer or resin or epoxy or thermoset$4 or thermoplastic$4 or thermo adj (set$6 or plastic$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
38 BRS	193	(throughhole or through adj hole or via adj hole or viahole) near4 ((photopolymer or polymer or resin or epoxy or thermoset$4 or thermoplastic$4 or thermo adj (set$6 or plastic$4)) near2 (cur$4 or harden$4 or consolidat$4 or ossif$4)) near4 (photopolymer or polymer or resin or epoxy or thermoset$4 or thermoplastic$4 or thermo adj (set$6 or plastic$4)) and (substrate or wafer or die or chip or ic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
39 BRS	193	(throughhole or through adj hole or via adj hole or viahole) near4 ((photopolymer or polymer or resin or epoxy or thermoplastic$4 or thermo adj (set$6 or plastic$4)) near2 (cur$4 or harden$4 or consolidat$4 or ossif$4)) near4 (photopolymer or polymer or resin or epoxy or thermoplastic$4 or thermo adj (set$6 or plastic$4)) and (substrate or wafer or die or chip or ic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

Type	Hits	Search Text	DBs
40 BRS	24	(throughhole or through adj hole or via adj hole or viahole) near4 ((photopolymer or polymer or resin or epoxy or thermoset$4 or thermoplastic$4 or thermo adj (set$6 or plastic$4)) near2 (cur$4 or harden$4 or consolidat$4 or ossif$4)) near4 (coat$4 or lin$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
41 BRS	1617	trepan$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
42 BRS	336075	drill$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
43 BRS	507324	throughhole or through adj hole or via adj hole or viahole	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
44 BRS	3503714	metal or copper or cvd	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
45 BRS	120667	cvd	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
46 BRS	0	trepan$4 near8 drill$4 same cvd near4 (metal or copper or cvd) near8 (throughhole or through adj hole or via adj hole or viahole)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
47 BRS	0	trepan$4 near8 drill$4 same cvd near8 (throughhole or through adj hole or viahole)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
48 BRS	0	trepan$4 near8 drill$4 and cvd near8 (throughhole or through adj hole or via adj hole or viahole)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

Type	Hits	Search Text	DBs
49	BRS	0	trepan$4 same drill$4 and cvd near8 (throughhole or through adj hole or via adj hole or viahole)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
50	BRS	454	trepan$4 same drill$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
51	BRS	22	trepan$4 same drill$4 same (throughhole or through adj hole or via adj hole or viahole)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
52	BRS	30778	frustoconical	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
53	BRS	304	frustoconical.ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
54	IS&R	2777	((438/761) or (438/667) or (438/637) or (438/640)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB